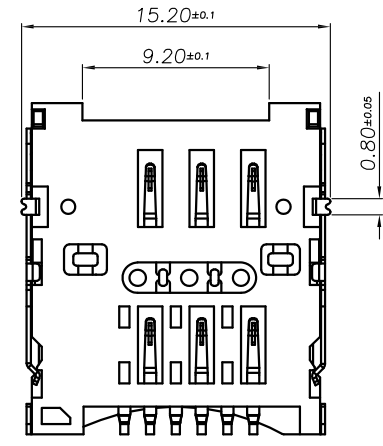
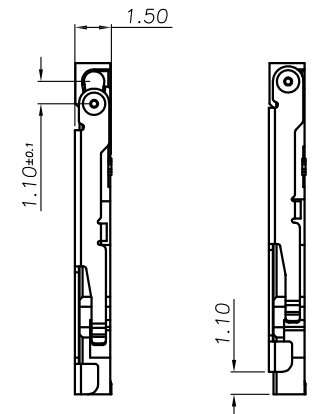
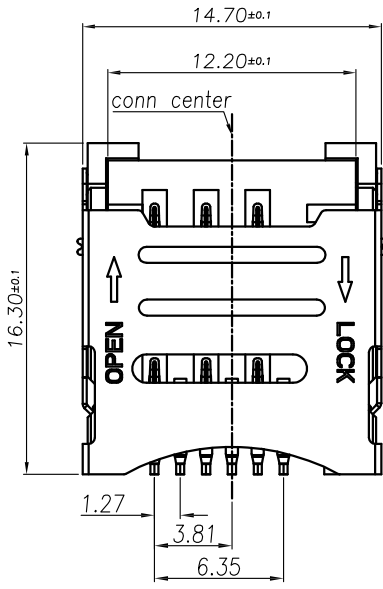
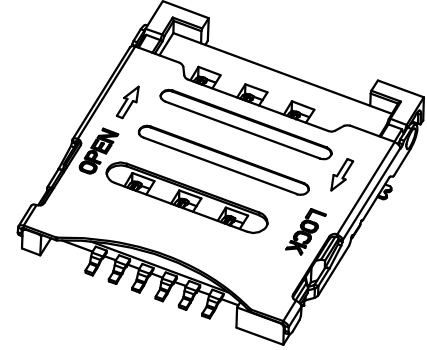
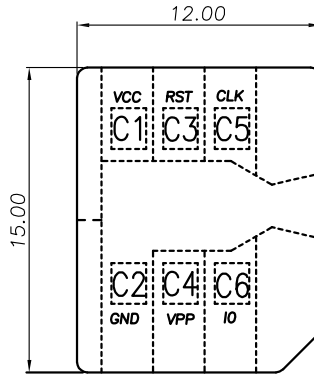
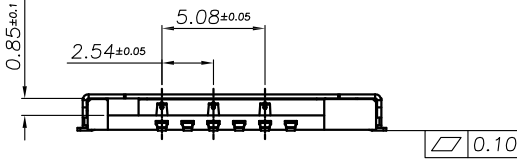


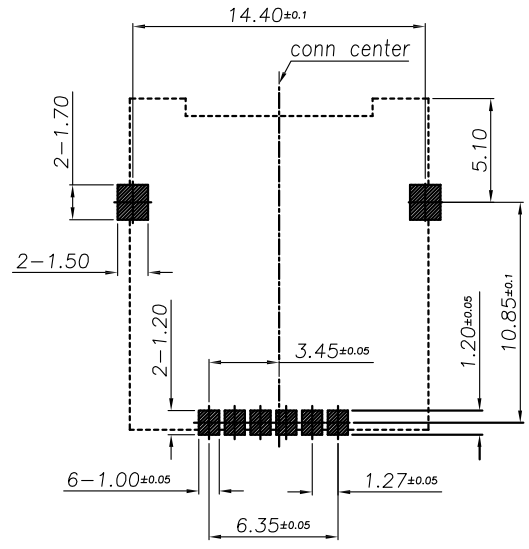
REV.	ECN.NO.	APPD.
A	/	/



*Electrical Characteristics:
 Contact Current Rating:0.5 Amperes.
 Dielectric Withstanding Voltage:AC500V r.m.s.
 Insulation Resistance:1000 MΩ Minimum.
 Contact Resistance:100 mΩ Maximum.
 *Environmental:
 Operating Temperature:-25°C~+90°C.
 *Environmental:
 Mating Cycles:5000~10,000 Insertions.
 *Mechanical Characteristics:
 Card Push Insertion/Out Force:1.4kgf. MAX
 Contact Separation Force:0.20kgf Minimum.
 *Material:
 Insulator:HI-Temp Plastic UL 94V-O Rated.
 Contact:Copper Alloy(t=0.15mm).
 Shell:Stainless Steel(t=0.20mm).
 Spring:SWP.



SD5211-100-G68
 G:半金G/Fu 6:LCP黑色



PIN NO.	NAME	PIN NO.	NAME
C1	VCC	C4	VPP
C2	GND	C5	CLK
C3	RST	C6	IO

RECOMMENDED PCB LAYOUT(Top View)
 GENERAL TOLERANCE ±0.05

TOLERANCE UNLESS OTHERWISE SPECIFIED	
.XXX ±0.10	.X' ±3'
.XX ±0.20	.XX' ±2'
.X ±0.30	

FLW 深圳市华联威电子科技有限公司
 HUA LIAN WEI TECHNOLOGY ELECTRONICS CO.;LTD.

APPROVED		PART NAME:	SD 卡座 高度1.5 SIM 掀盖式6PIN			
CHECKED		PART No:	SD5211-100-G68		C	
DRAWN	chenyiting	PROJECTION:	UNIT:	SCALE:	SHEET:	REV.
DATE	2023.04.19		mm	1:1	10F1	A